

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Application Number : 10/553,470 Confirmation No.: 8935  
: National Phase of International App'l. No. PCT/DE2004/000801  
Applicant Ralf LERNER  
Filed : May 19, 2006  
Title : MONITORING THE REDUCTION OF THICKNESS AS  
MATERIAL IS REMOVED FROM A WAFER COMPOSITE AND  
TEST STRUCTURE FOR MONITORING REMOVAL OF  
MATERIAL  
TC/Art Unit : 2818  
Examiner: : Lopez Esquerro, Andres  
Docket No. : 60291.000041  
Customer No. : 21967

**MAIL STOP AMENDMENTS**  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**RESPONSE TO NON-FINAL OFFICE ACTION UNDER 37 C.F.R. § 1.111**  
**AND PETITION FOR TWO-MONTH EXTENSION OF TIME UNDER 37 C.F.R. § 1.136**

Sir:

**AMENDMENT**

**Amendments to the Claims** appear in the Listing of Claims beginning on page 2 of this paper.

**Remarks** appear on page 7 of this paper.

**Substitute Specification** (clean copy) is Attachment A.

**Substitute Specification** (marked-up copy) is Attachment B.